

What is claimed is:

1. A surface-mounted electronic component module comprising:

5 a wiring substrate having wiring patterns formed on one side and external connection terminals formed on the other side, the wiring patterns and the external connection terminals being connected with each other by via holes or through holes;

10 a plurality of electronic component devices mounted on the one side of the wiring substrate; and
an exterior resin layer formed on the wiring substrate which covers the plurality of electronic component devices,

15 wherein at least one of the plurality of electronic component devices is fastened face up to the one side of the wiring substrate, the connection terminal of the electronic component device fastened face up and the wiring pattern or the connection terminal of another
20 electronic component device being connected with each other by wire.

2. The surface-mounted electronic component module according to claim 1, wherein at least one of the wire bondings connecting the connection terminal of the electronic component device fastened face up and the wiring pattern or the connection terminal of the another

electronic component device, has a predetermined inductance as a circuit element.

3. The surface-mounted electronic component module
5 according to claim 1, wherein the electronic component device fastened face up to the one side of the wiring substrate is fastened to the wiring substrate by a bond made of conductive paste.

10 4. The surface-mounted electronic component module according to claim 2, wherein the electronic component device fastened face up to the one side of the wiring substrate is fastened to the wiring substrate by a bond made of conductive paste.

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5. A surface-mounted electronic component module comprising:

20 a wiring substrate having wiring patterns formed on one side and external connection terminals formed on the other side, the wiring patterns and the external connection terminals being connected with each other by via holes or through holes;

25 a semiconductor chip mounted on the one side of the wiring substrate, the semiconductor chip forming a switch for changing over the opening/closing of radio frequency transmission/ reception signals and a decoder circuit for controlling the switch changeover operations;

a surface acoustic wave filter connected to the switch; and

an exterior resin layer formed on the wiring substrate which covers the semiconductor chip and the 5 surface acoustic wave filter,

wherein at least one of the semiconductor chip and the surface acoustic wave filter is fastened face up to the one side of the wiring substrate, the connection terminal of the at least one of the semiconductor chip and 10 the surface acoustic wave filter, fastened face up, and the wiring pattern or the connection terminal of the other being connected with each other through wire bonding.

6. The surface-mounted electronic component module 15 according to claim 5, wherein connection terminals connected through the wire bonding are signal terminals, the wire bonding having a predetermined inductance as a circuit element.

20 7. The surface-mounted electronic component module according to claim 5, wherein at least one of the semiconductor chip and the surface acoustic wave filter, fastened to the one side of the wiring substrate, is fastened to the wiring substrate by a bond made of 25 conductive paste.

8. A method for manufacturing a surface-mounted

electronic component module comprising the steps of:

providing a wiring substrate having wiring patterns formed on one side and external connection terminals formed on the other side, the wiring patterns on the one side and the external connection terminals on the other side being connected with each other by via holes or through holes;

providing a semiconductor chip having connection terminals disposed on at least the same surface;

10 providing a surface acoustic wave filter having connection terminals disposed on at least the same surface, the surface acoustic wave filter having a closed gap immediately above the portion where a transducer is formed;

15 fastening both or at least one of the semiconductor chip and the surface acoustic wave filter to the wiring pattern surface of the wiring substrate such that the connection terminal does not face the wiring pattern surface;

20 making by wire at least one of three connections, connection between the connection terminal of the semiconductor chip and the wiring pattern of the wiring substrate, connection between the connection terminal of the surface acoustic wave filter and the wiring pattern of the wiring substrate, and connection between the connection terminal of the semiconductor chip and the connection terminal of the surface acoustic wave filter;

and

coating the wiring substrate with exterior resin in such a manner as to cover the semiconductor chip and the surface acoustic wave filter fastened to the wiring
5 substrate.